

+3.3V Programmable LVDS Transmitter 18-Bit Flat Panel Display (FPD) Link -65 MHz

Check for Samples: [DS90CF363B](#)

FEATURES

- No Special Start-up Sequence Required between Clock/Data and /PD Pins. Input Signal (Clock and Data) can be Applied Either Before or After the Device is Powered.
- Support Spread Spectrum Clocking up to 100KHz Frequency Modulation & Deviations of $\pm 2.5\%$ Center Spread or -5% Down Spread.
- "Input Clock Detection" Feature will Pull all LVDS Pairs to Logic Low when Input Clock is Missing and when /PD Pin is Logic High.
- 18 to 68 MHz Shift Clock Support
- Best-in-Class Set & Hold Times on TxINPUTs
- Tx Power Consumption < 130 mW (typ) @65MHz Grayscale
- 40% Less Power Dissipation than BiCMOS Alternatives
- Tx Power-Down Mode < 37 μ W (typ)
- Supports VGA, SVGA, XGA and Dual Pixel SXGA.
- Narrow Bus Reduces Cable Size and Cost
- Up to 1.3 Gbps Throughput
- Up to 170 Megabytes/sec Bandwidth

- 345 mV (typ) Swing LVDS Devices for Low EMI
- PLL Requires no External Components
- Compatible with TIA/EIA-644 LVDS Standard
- Low Profile 48-lead TSSOP Package
- Improved Replacement for:
 - SN75LVDS84, DS90CF363A

DESCRIPTION

The DS90CF363B transmitter converts 21 bits of CMOS/TTL data into three LVDS (Low Voltage Differential Signaling) data streams. A phase-locked transmit clock is transmitted in parallel with the data streams over a fourth LVDS link. Every cycle of the transmit clock 21 bits of input data are sampled and transmitted. At a transmit clock frequency of 65 MHz, 18 bits of RGB data and 3 bits of LCD timing and control data (FPLINE, FPFRAME, DRDY) are transmitted at a rate of 455 Mbps per LVDS data channel. Using a 65 MHz clock, the data throughput is 170 Mbytes/sec. The DS90CF363B is fixed as a Falling edge strobe transmitter and will interoperate with a Falling edge strobe Receiver (DS90CF366) without any translation logic.

This chipset is an ideal means to solve EMI and cable size problems associated with wide, high speed TTL interfaces.

Block Diagram

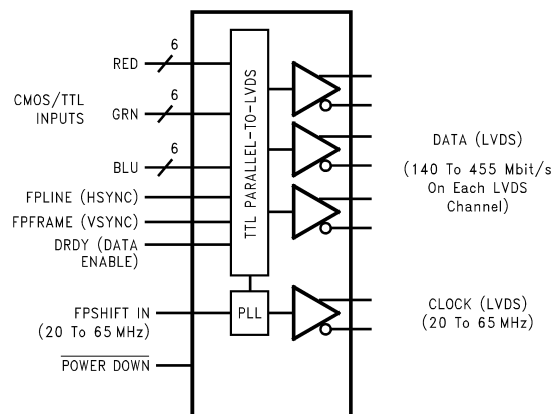


Figure 1. DS90CF363B
See Package Number DGG0048A



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings ⁽¹⁾⁽²⁾

	Value	Unit
Supply Voltage (V_{CC})	-0.3 to +4	V
CMOS/TTL Input Voltage	-0.3 to ($V_{CC} + 0.3$)	V
LVDS Driver Output Voltage	-0.3 to ($V_{CC} + 0.3$)	V
LVDS Output Short Circuit Duration	Continuous	
Junction Temperature	+150	°C
Storage Temperature	-65 to +150	°C
Lead Temperature (Soldering, 4 sec)	+260	°C
Maximum Package Power Dissipation Capacity @ 25°C		
DGG-48 (TSSOP) Package: DS90CF363B	1.98	W
Package Derating: DS90CF363B	16 mW/°C above +25°C	
ESD Rating (HBM, 1.5 kΩ, 100 pF)	7	kV
ESD Rating (EIAJ, 0Ω, 200 pF)	500	V

- (1) Absolute Maximum Ratings are those values beyond which the safety of the device cannot be verified. They are not meant to imply that the device should be operated at these limits. Electrical Characteristics specify conditions for device operation.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.

Recommended Operating Conditions

	Min	Nom	Max	Units
Supply Voltage (V_{CC})	3.0	3.3	3.6	V
Operating Free Air Temperature (T_A)	-10	+25	+70	°C
Supply Noise Voltage (V_{CC})			200	mV _{PP}
TxCLKIN frequency	18		68	MHz

Electrical Characteristics ⁽¹⁾

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ ⁽²⁾	Max	Units
CMOS/TTL DC SPECIFICATIONS						
V _{IH}	High Level Input Voltage		2.0		V _{CC}	V
V _{IL}	Low Level Input Voltage		GND		0.8	V
V _{CL}	Input Clamp Voltage	I _{CL} = -18 mA		-0.79	-1.5	V
I _{IN}	Input Current	V _{IN} = 0.4V, 2.5V or V _{CC}		+1.8	+10	μA
		V _{IN} = GND	-10	0		μA
LVDS DC SPECIFICATIONS						
V _{OD}	Differential Output Voltage	R _L = 100Ω	250	345	450	mV
ΔV _{OD}	Change in V _{OD} between complimentary output states				35	mV
V _{OS}	Offset Voltage ⁽³⁾		1.13	1.25	1.38	V
ΔV _{OS}	Change in V _{OS} between complimentary output states				35	mV
I _{OS}	Output Short Circuit Current	V _{OUT} = 0V, R _L = 100Ω		-3.5	-5	mA

- (1) Current into device pins is defined as positive. Current out of device pins is defined as negative. Voltages are referenced to ground unless otherwise specified (except V_{OD} and ΔV_{OD}).
- (2) Typical values are given for $V_{CC} = 3.3V$ and $T_A = +25^\circ C$ unless specified otherwise.
- (3) V_{OS} previously referred as V_{CM} .

Electrical Characteristics⁽¹⁾ (continued)

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ ⁽²⁾	Max	Units
I _{oz}	Output TRI-STATE Current	Power Down = 0V, V _{OUT} = 0V or V _{CC}		±1	±10	μA
TRANSMITTER SUPPLY CURRENT						
ICCTW	Transmitter Supply Current Worst Case	R _L = 100Ω, C _L = 5 pF, Worst Case Pattern (Figure 2 and Figure 5) " Typ " values are given for V _{CC} = 3.6V and T _A = +25°C, " Max " values are given for V _{CC} = 3.6V and T _A = -10°C	f = 25 MHz		29	40 mA
			f = 40 MHz		34	45 mA
			f = 65 MHz		42	55 mA
ICCTG	Transmitter Supply Current 16 Grayscale	R _L = 100Ω, C _L = 5 pF, 16 Grayscale Pattern (Figure 3 and Figure 5) " Typ " values are given for V _{CC} = 3.6V and T _A = +25°C, " Max " values are given for V _{CC} = 3.6V and T _A = -10°C	f = 25 MHz		28	40 mA
			f = 40 MHz		32	45 mA
			f = 65 MHz		39	50 mA
ICCTZ	Transmitter Supply Current Power Down	Power Down = Low Driver Outputs in TRI-STATE under Power Down Mode		11	150	μA

Recommended Transmitter Input Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified

Symbol	Parameter	Min	Typ	Max	Units
TCIT	TxCLK IN Transition Time (Figure 6)			5	ns
TCIP	TxCLK IN Period (Figure 7)	14.7	T	50.0	ns
TCIH	TxCLK IN High Time (Figure 7)	0.35T	0.5T	0.65T	ns
TCIL	TxCLK IN Low Time (Figure 7)	0.35T	0.5T	0.65T	ns
TXIT	TxIN, and Power Down pin transition Time	1.5		6.0	ns
TXPD	Minimum pulse width for Power Down pin signal	1			us

Transmitter Switching Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified

Symbol	Parameter	Min	Typ	Max	Units
LLHT	LVDS Low-to-High Transition Time (Figure 5)		0.75	1.4	ns
LHLT	LVDS High-to-Low Transition Time (Figure 5)		0.75	1.4	ns
TPPos0	Transmitter Output Pulse Position for Bit 0 (Figure 12) ⁽¹⁾	f = 65 MHz	-0.20	0	+0.20 ns
TPPos1	Transmitter Output Pulse Position for Bit 1		2.00	2.20	2.40 ns
TPPos2	Transmitter Output Pulse Position for Bit 2		4.20	4.40	4.60 ns
TPPos3	Transmitter Output Pulse Position for Bit 3		6.39	6.59	6.79 ns
TPPos4	Transmitter Output Pulse Position for Bit 4		8.59	8.79	8.99 ns
TPPos5	Transmitter Output Pulse Position for Bit 5		10.70	10.99	11.19 ns
TPPos6	Transmitter Output Pulse Position for Bit 6		12.99	13.19	13.39 ns

(1) The Minimum and Maximum Limits are based on statistical analysis of the device performance over process, voltage, and temperature ranges. This parameter is functionality tested only on Automatic Test Equipment (ATE).

Transmitter Switching Characteristics (continued)

Over recommended operating supply and temperature ranges unless otherwise specified

Symbol	Parameter		Min	Typ	Max	Units
TPPos0	Transmitter Output Pulse Position for Bit 0 (Figure 12) ⁽¹⁾	f = 40 MHz	-0.25	0	+0.25	ns
TPPos1	Transmitter Output Pulse Position for Bit 1		3.32	3.57	3.82	ns
TPPos2	Transmitter Output Pulse Position for Bit 2		6.89	7.14	7.39	ns
TPPos3	Transmitter Output Pulse Position for Bit 3		10.46	10.71	10.96	ns
TPPos4	Transmitter Output Pulse Position for Bit 4		14.04	14.29	14.54	ns
TPPos5	Transmitter Output Pulse Position for Bit 5		17.61	17.86	18.11	ns
TPPos6	Transmitter Output Pulse Position for Bit 6		21.18	21.43	21.68	ns
TPPos0	Transmitter Output Pulse Position for Bit 0 (Figure 12) ⁽¹⁾	f = 25MHz	-0.45	0	+0.45	ns
TPPos1	Transmitter Output Pulse Position for Bit 1		5.26	5.71	6.16	ns
TPPos2	Transmitter Output Pulse Position for Bit 2		10.98	11.43	11.88	ns
TPPos3	Transmitter Output Pulse Position for Bit 3		16.69	17.14	17.59	ns
TPPos4	Transmitter Output Pulse Position for Bit 4		22.41	22.86	23.31	ns
TPPos5	Transmitter Output Pulse Position for Bit 5		28.12	28.57	29.02	ns
TPPos6	Transmitter Output Pulse Position for Bit 6		33.84	34.29	34.74	ns
TSTC	TxIN Setup to TxCLK IN (Figure 7)		2.5			ns
THTC	TxIN Hold to TxCLK IN (Figure 7)		0.5			ns
TCCD	TxCLK IN to TxCLK OUT Delay (Figure 8) 50% duty cycle input clock is assumed, T _A = -10°C, and 65MHz for "Min", T _A = 70°C, and 25MHz for "Max", V _{CC} = 3.6V		3.011		6.082	ns
SSCG	Spread Spectrum Clock support; Modulation frequency with a linear profile ⁽²⁾	f = 25 MHz		100KHz ± 2.5%/-5%		
		f = 40 MHz		100KHz ± 2.5%/-5%		
		f = 65 MHz		100KHz ± 2.5%/-5%		
TPLLS	Transmitter Phase Lock Loop Set (Figure 9)				10	ms
TPDD	Transmitter Power Down Delay (Figure 11)				100	ns

(2) Care must be taken to ensure TSTC and THTC are met so input data are sampling correctly. This SSCG parameter only shows the performance of tracking Spread Spectrum Clock applied to TxCLK IN pin, and reflects the result on TxCLKOUT+ and TxCLK- pins.

AC Timing Diagrams

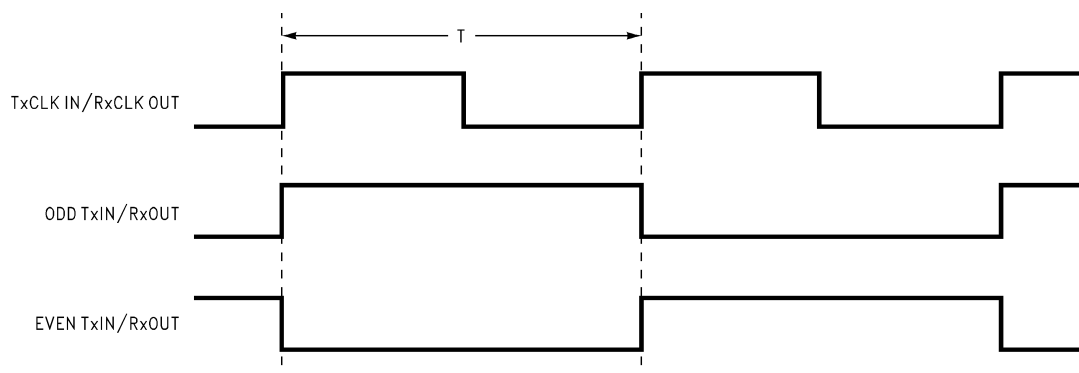


Figure 2. "Worst Case" Test Pattern

Device Pin Name	Signal	Signal Pattern	Signal Frequency
TxCLK IN/RxCLK OUT	Dot Clk		f
TxIN0/RxOUT0	R0		f/16
TxIN1/RxOUT1	R1		f/8
TxIN2/RxOUT2	R2		f/4
TxIN3/RxOUT3	R3		f/2
TxIN4/RxOUT4	R4		Steady State, Low
TxIN5/RxOUT5	R5		Steady State, Low
TxIN6/RxOUT6	G0		f/16
TxIN7/RxOUT7	G1		f/8
TxIN8/RxOUT8	G2		f/4
TxIN9/RxOUT9	G3		f/2
TxIN10/RxOUT10	G4		Steady State, Low
TxIN11/RxOUT11	G5		Steady State, Low
TxIN12/RxOUT12	B0		f/16
TxIN13/RxOUT13	B1		f/8
TxIN14/RxOUT14	B2		f/4
TxIN15/RxOUT15	B3		f/2
TxIN16/RxOUT16	B4		Steady State, Low
TxIN17/RxOUT17	B5		Steady State, Low
TxIN18/RxOUT18	HSYNC		Steady State, High
TxIN19/RxOUT19	VSYNC		Steady State, High
TxIN20/RxOUT20	ENA		Steady State, High

The worst case test pattern produces a maximum toggling of digital circuits, LVDS I/O and CMOS/TTL I/O.

The 16 grayscale test pattern tests device power consumption for a "typical" LCD display pattern. The test pattern approximates signal switching needed to produce groups of 16 vertical stripes across the display.

Figure 2 and Figure 3 show a falling edge data strobe (TxCLK IN/RxCLK OUT).

Recommended pin to signal mapping. Customer may choose to define differently.

Figure 3. "16 Grayscale" Test Pattern

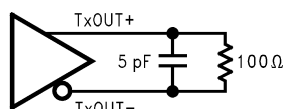


Figure 4. DS90CF363B (Transmitter) LVDS Output Load

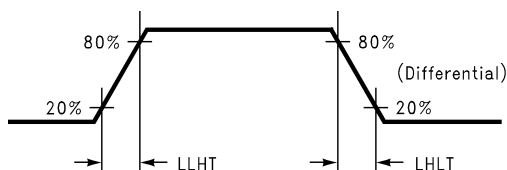


Figure 5. DS90CF363B (Transmitter) LVDS Transition Times

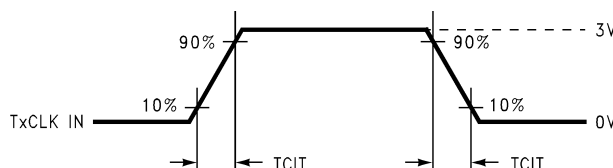


Figure 6. DS90CF363B (Transmitter) Input Clock Transition Time

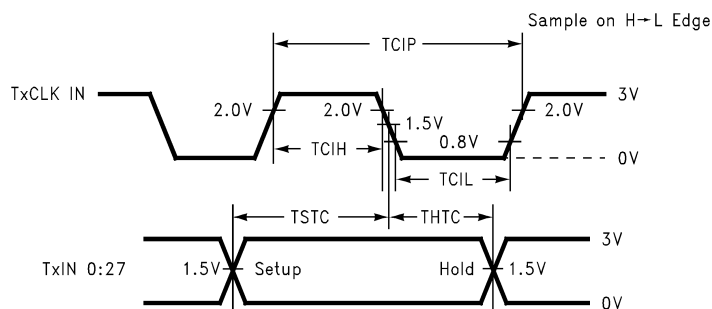


Figure 7. DS90CF363B (Transmitter) Setup/Hold and High/Low Times (Falling Edge Strobe)

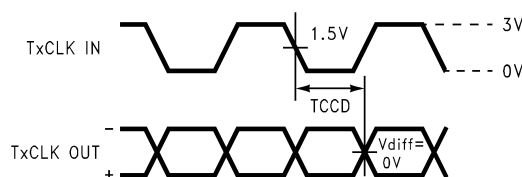


Figure 8. DS90CF363B (Transmitter) Clock In to Clock Out Delay (Falling Edge Strobe)

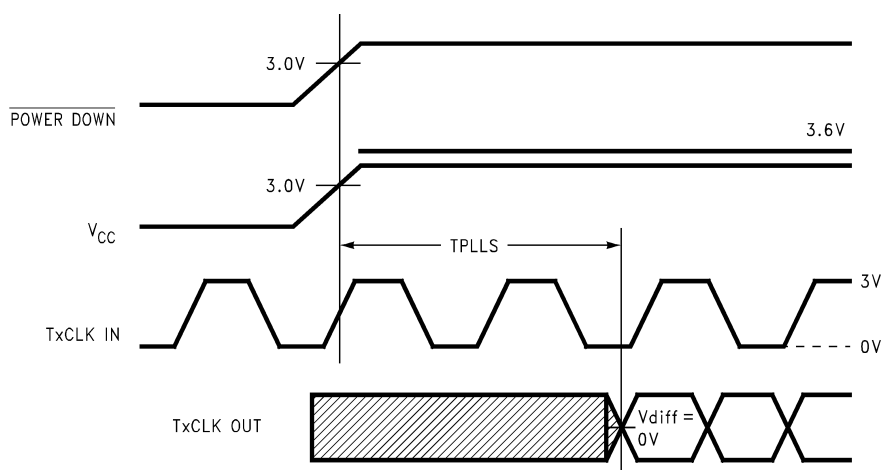


Figure 9. DS90CF363B (Transmitter) Phase Lock Loop Set Time

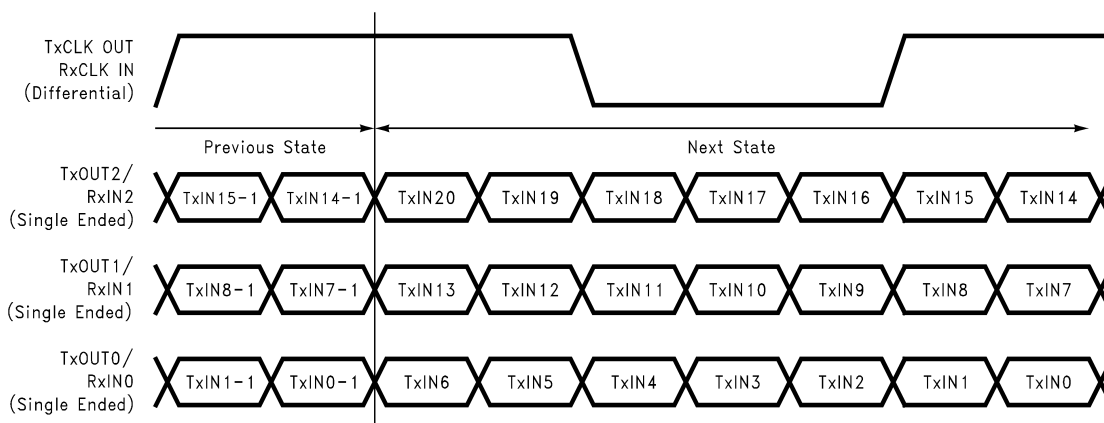


Figure 10. 21 Parallel TTL Data Inputs Mapped to LVDS Outputs

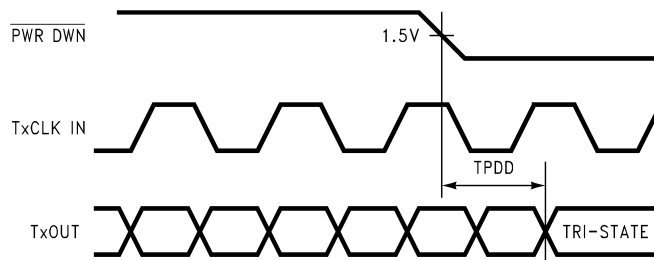


Figure 11. Transmitter Power Down Delay

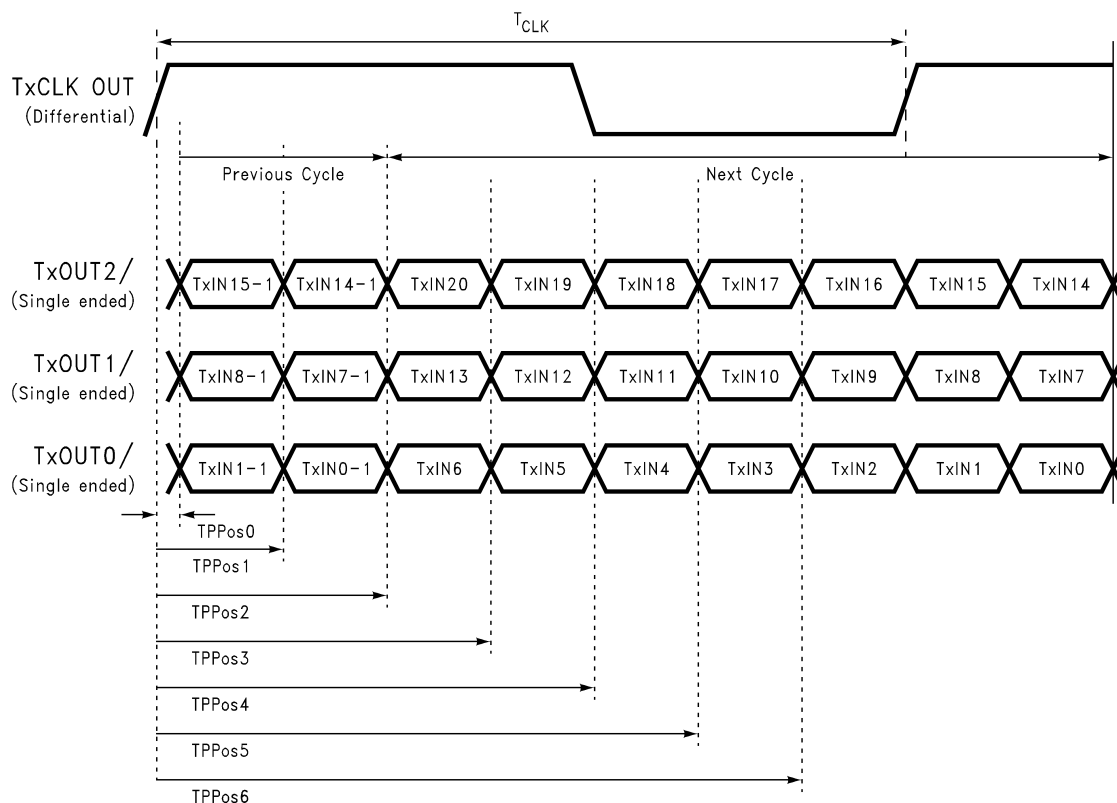


Figure 12. Transmitter LVDS Output Pulse Position Measurement

DS90CF363B PIN DESCRIPTIONS — FPD LINK TRANSMITTER

Pin Name	I/O	No.	Description
TxIN	I	21	TTL level input. This includes: 6 Red, 6 Green, 6 Blue, and 3 control lines—FPLINE, FPFRAME and DRDY (also referred to as HSYNC, VSYNC, Data Enable).
TxOUT+	O	3	Positive LVDS differential data output.
TxOUT-	O	3	Negative LVDS differential data output.
FPSHIFT IN	I	1	TTL level clock input. The falling edge acts as data strobe. Pin name TxCLK IN.
TxCLK OUT+	O	1	Positive LVDS differential clock output.
TxCLK OUT-	O	1	Negative LVDS differential clock output.
PWR DOWN	I	1	TTL level input. Assertion (low input) TRI-STATES the outputs, ensuring low current at power down. See Applications Information .
V _{CC}	I	4	Power supply pins for TTL inputs.
GND	I	4	Ground pins for TTL inputs.
PLL V _{CC}	I	1	Power supply pin for PLL.
PLL GND	I	2	Ground pins for PLL.
LVDS V _{CC}	I	1	Power supply pin for LVDS outputs.
LVDS GND	I	3	Ground pins for LVDS outputs.
NC		1	No connect

APPLICATIONS INFORMATION

The DS90CF363B are backward compatible with the DS90C363/DS90CF363A and are a pin-for-pin replacement.

This device may also be used as a replacement for the DS90CF563 (5V, 65MHz) and DS90CF561 (5V, 40MHz) FPD-Link Transmitters with certain considerations/modifications:

1. Change 5V power supply to 3.3V. Provide this supply to the V_{CC}, LVDS V_{CC} and PLL V_{CC} of the transmitter.

TRANSMITTER INPUT PINS

The DS90CF363B transmitter input and control inputs accept 3.3V LVTTTL/LVCMOS levels. They are not 5V tolerant.

TRANSMITTER INPUT CLOCK/DATA SEQUENCING

The DS90CF363B does not require any special requirement for sequencing of the input clock/data and PD (PowerDown) signal. The DS90CF363B offers a more robust input sequencing feature where the input clock/data can be inserted after the release of the PD signal. In the case where the clock/data is stopped and reapplied, such as changing video mode within Graphics Controller, it is not necessary to cycle the PD signal. However, there are in certain cases where the PD may need to be asserted during these mode changes. In cases where the source (Graphics Source) may be supplying an unstable clock or spurious noisy clock output to the LVDS transmitter, the LVDS Transmitter may attempt to lock onto this unstable clock signal but is unable to do so due to the instability or quality of the clock source. The PD signal in these cases should then be asserted once a stable clock is applied to the LVDS transmitter. Asserting the PWR DOWN pin will effectively place the device in reset and disable the PLL, enabling the LVDS Transmitter into a power saving standby mode. However, it is still generally a good practice to assert the PWR DOWN pin or reset the LVDS transmitter whenever the clock/data is stopped and reapplied but it is not mandatory for the DS90CF363B.

SPREAD SPECTRUM CLOCK SUPPORT

The DS90CF363B can support Spread Spectrum Clocking signal type inputs. The DS90CF363B outputs will accurately track Spread Spectrum Clock/Data inputs with modulation frequencies of up to 100KHz (max.) with either center spread of $\pm 2.5\%$ or down spread -5% deviations.

POWER SOURCES SEQUENCE

In typical applications, it is recommended to have V_{CC}, LVDS V_{CC} and PLL V_{CC} from the same power source with three separate de-coupling bypass capacitor groups. There is no requirement on which VCC entering the device first.

Pin Diagram

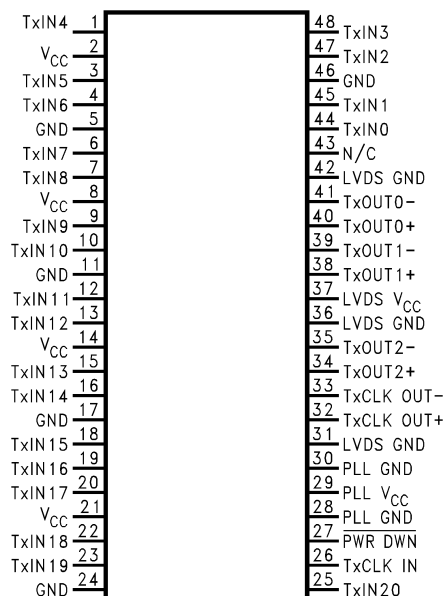
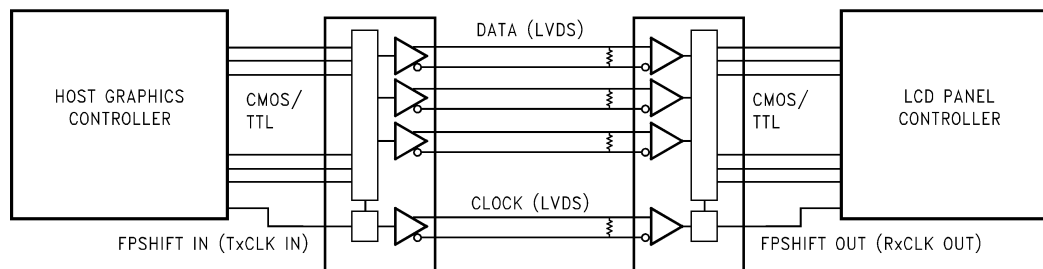


Figure 13.

Typical Application



REVISION HISTORY

Changes from Revision C (April 2013) to Revision D	Page
• Changed layout of National Data Sheet to TI format	9

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DS90CF363BMT/NOPB	Active	Production	TSSOP (DGG) 48	38 TUBE	Yes	SN	Level-2-260C-1 YEAR	-10 to 70	DS90CF363BMT
DS90CF363BMT/NOPB.A	Active	Production	TSSOP (DGG) 48	38 TUBE	Yes	SN	Level-2-260C-1 YEAR	-10 to 70	DS90CF363BMT
DS90CF363BMT/NOPB.B	Active	Production	TSSOP (DGG) 48	38 TUBE	Yes	SN	Level-2-260C-1 YEAR	-10 to 70	DS90CF363BMT
DS90CF363BMTX/NOPB	Active	Production	TSSOP (DGG) 48	1000 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-10 to 70	DS90CF363BMT
DS90CF363BMTX/NOPB.A	Active	Production	TSSOP (DGG) 48	1000 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-10 to 70	DS90CF363BMT
DS90CF363BMTX/NOPB.B	Active	Production	TSSOP (DGG) 48	1000 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-10 to 70	DS90CF363BMT

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS90CF363BMTX/NOPB	TSSOP	DGG	48	1000	330.0	24.4	8.6	13.2	1.6	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

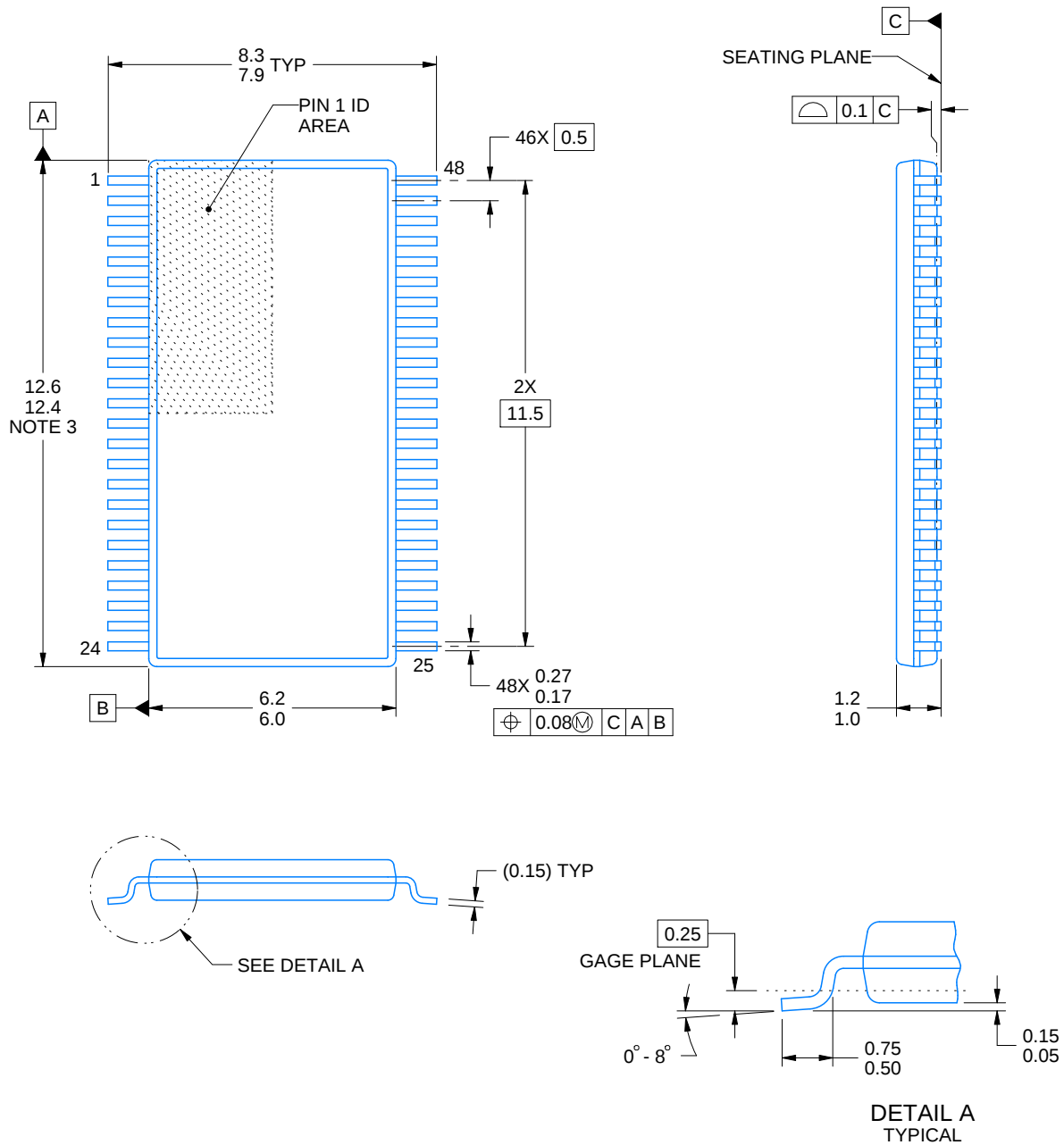
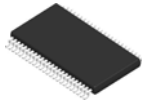
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS90CF363BMTX/NOPB	TSSOP	DGG	48	1000	356.0	356.0	45.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
DS90CF363BMT/NOPB	DGG	TSSOP	48	38	495	10	2540	5.79
DS90CF363BMT/NOPB.A	DGG	TSSOP	48	38	495	10	2540	5.79
DS90CF363BMT/NOPB.B	DGG	TSSOP	48	38	495	10	2540	5.79



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NOTES:

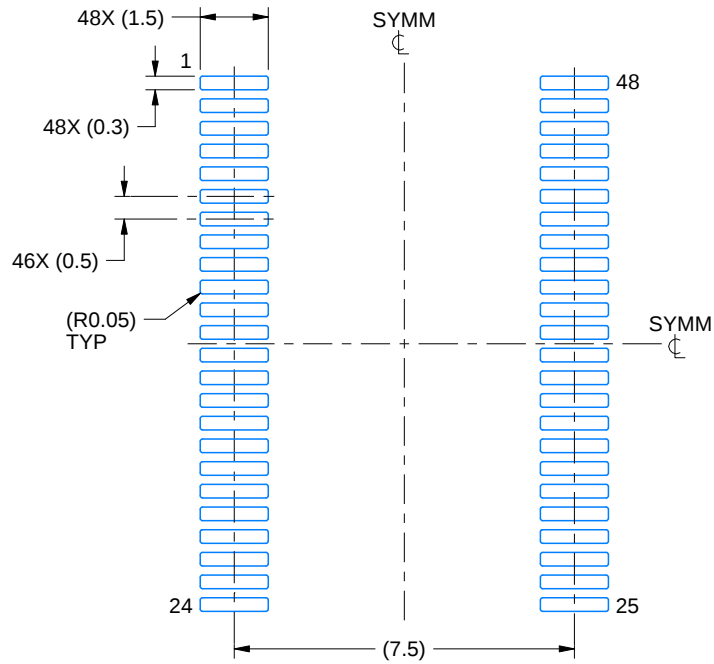
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

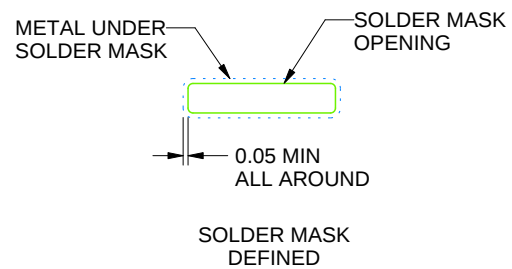
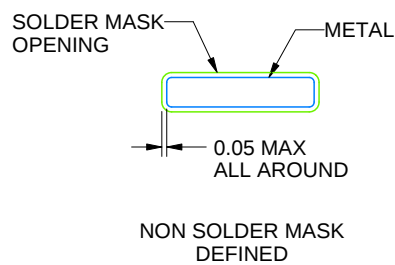
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4214859/B 11/2020

NOTES: (continued)

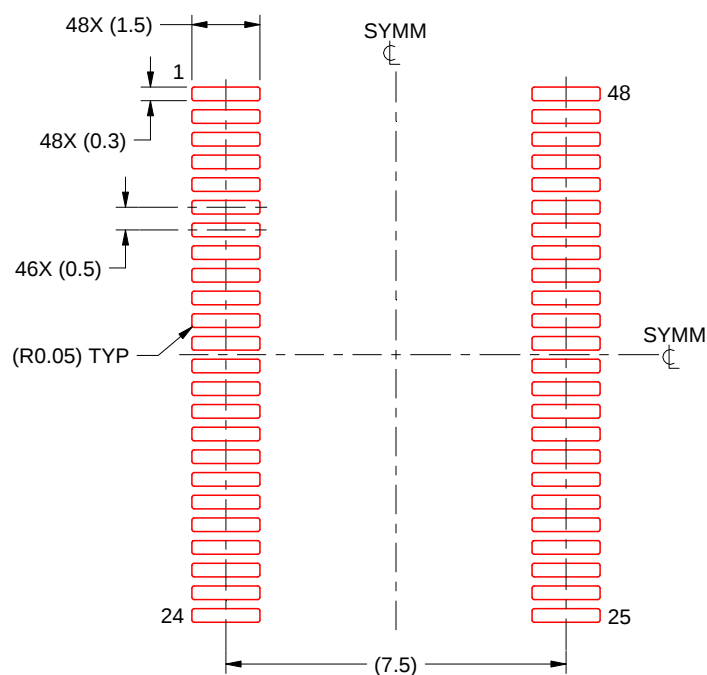
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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